

**General Description**

The SJ80N039 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a wide variety of applications.

**Features**

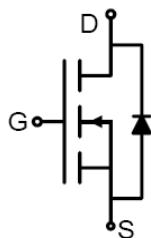
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

**Application**

- PWM Applications
- Load Switch
- Power Management

**Key Performance Parametes**

Parameter	Value	Unit
$V_{DS}$	80	V
$R_{DS(ON)}\_TYP$	4.3	mΩ
$I_D$	148	A
$Q_G$	193	nC



Schematic Diagram



TO-220 top view

**Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ80N039	SJ80N039	TO-220	Tube	\	\	1000 Pcs

**Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	80	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0\text{V}$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_c=25^\circ\text{C}$ )	148	A
	Drain Current-Continuous( $T_c=100^\circ\text{C}$ )	93	A
$I_{DM}$ (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	592	A
$P_D$	Maximum Power Dissipation( $T_c=25^\circ\text{C}$ )	250	W
	Maximum Power Dissipation( $T_c=100^\circ\text{C}$ )	100	W
$E_{AS}$	Avalanche energy (Note 2)	756	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	°C

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.5	°C/W



## 80V N-Channel Trench Power MOSFET

Table 3. Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	80			V
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	2		4	V
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=15\text{A}$		27.5		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=40\text{A}$		4.3	5.2	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$		8247		pF
$C_{\text{oss}}$	Output Capacitance			499		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			350		pF
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1.0\text{MHz}$		0.55		$\Omega$
<b>Switching Parameters</b>						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$ , $V_{\text{DS}}=40\text{V}$ , $R_L=1\Omega$ , $R_{\text{GEN}}=3\Omega$		55		nS
$t_r$	Turn-on Rise Time			40		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			115		nS
$t_f$	Turn-Off Fall Time			47		nS
$Q_g$	Total Gate Charge	$V_{\text{GS}}=10\text{V}$ , $V_{\text{DS}}=40\text{V}$ , $I_{\text{D}}=40\text{A}$		193		nC
$Q_{\text{gs}}$	Gate-Source Charge			32		nC
$Q_{\text{gd}}$	Gate-Drain Charge			72		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{\text{SD}}$	Source-Drain Current (Body Diode)				148	A
$V_{\text{SD}}$	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=40\text{A}$			1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=500\text{A}/\mu\text{s}$		16		ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$I_F=20\text{A}$ , $dI/dt=500\text{A}/\mu\text{s}$		70		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E<sub>AS</sub> condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=40\text{V}$ ,  $V_G=10\text{V}$ ,  $R_g=25\Omega$ ,  $L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



## Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

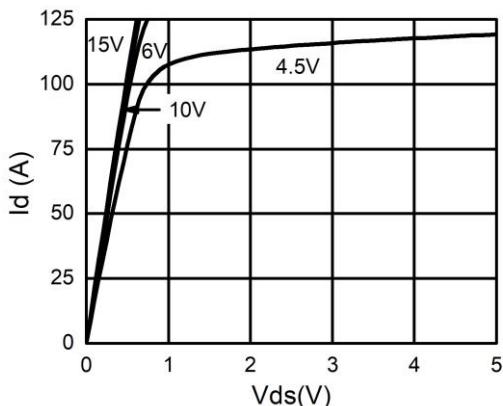


Figure 2. Transfer Characteristics

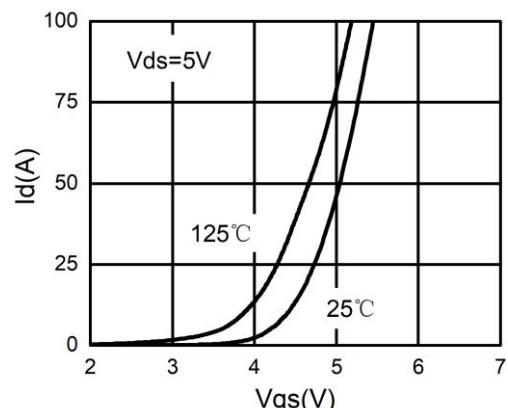


Figure 3. Power Dissipation

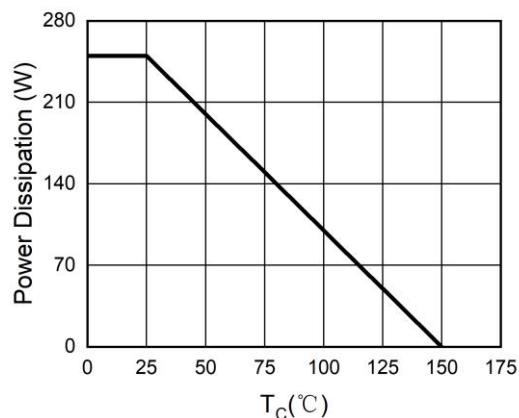
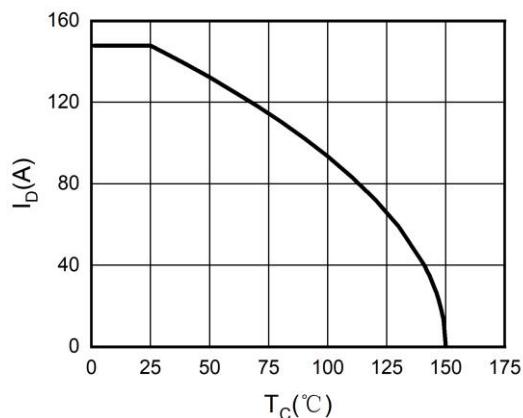
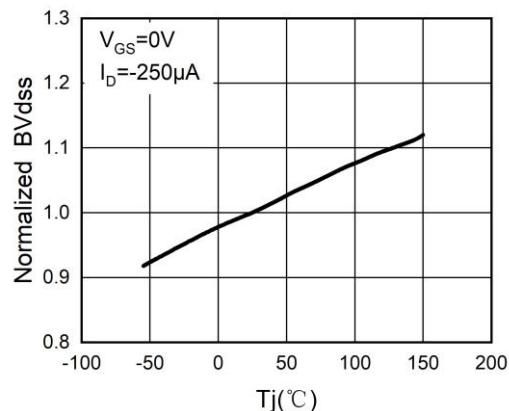
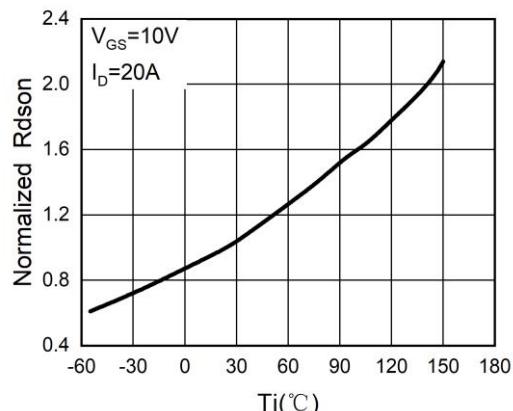
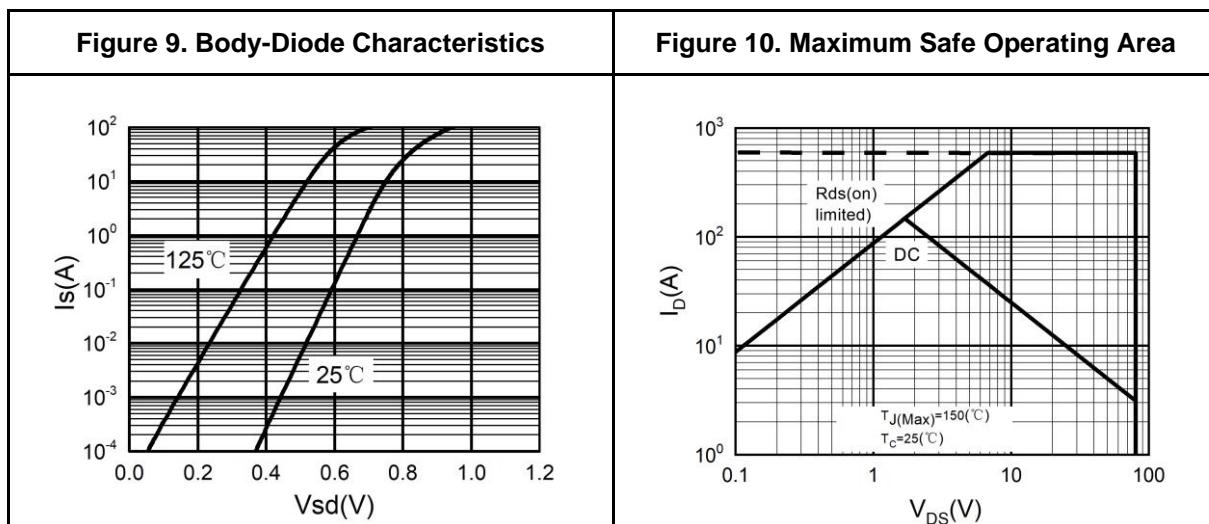
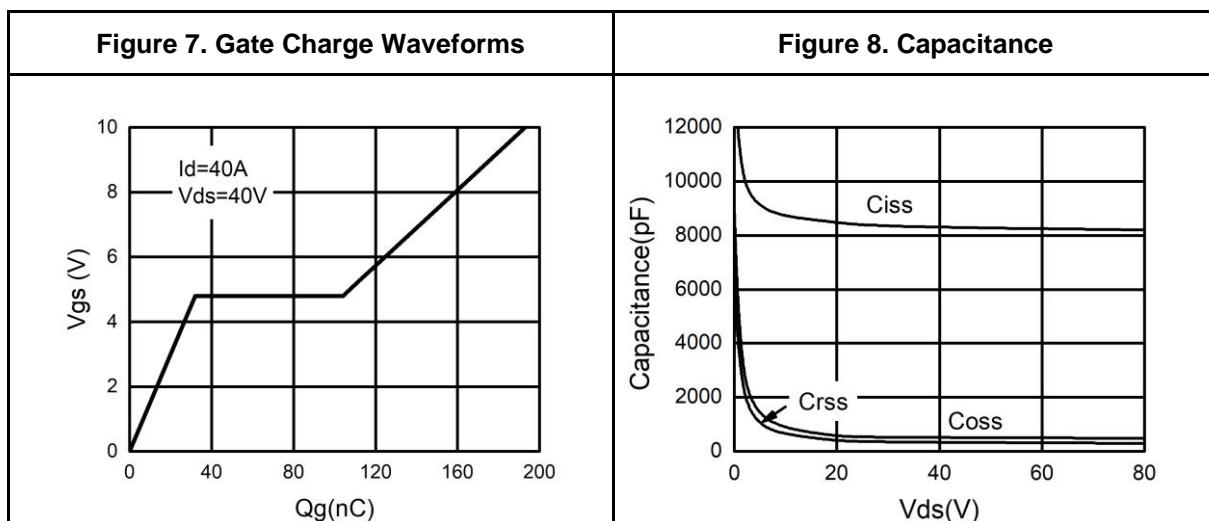


Figure 4. Drain Current

Figure 5. BV<sub>DSS</sub> vs Junction TemperatureFigure 6. R<sub>DSON</sub> vs Junction Temperature

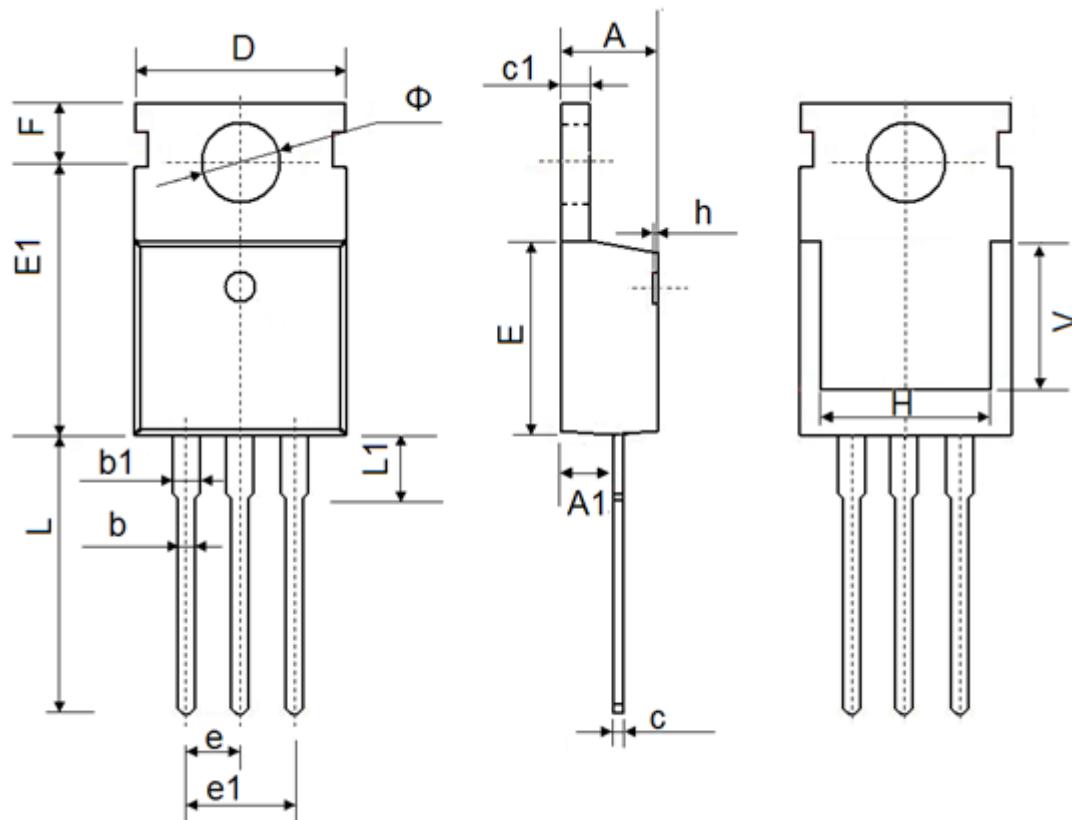


## Typical Electrical And Thermal Characteristics (Curves)





## TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157



## Attention

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